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Product Change Notification - JAON-15BYTH145

Date: 13 Jun 2016
Product Category: RF and Security; 8-bit Microcontrollers
Notification subject: CCB 2597 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 90K and 120K wafer technologies available in 8L SOIJ package at MTAI
Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 90K and 120K wafer technologies available in 8L SOIJ package at MTAI assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

June 2016

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Summary Table:

	June 2016				
	WW	22	23	24	25
Initial PCN Issue Date			X		
Qual Report Availability					X
Final PCN Issue Date					X

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
June 13, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-15BYTH145_Qual_Plan.pdf](#)
 - [PCN_JAON-15BYTH145_Affected_CPN.pdf](#)
 - [PCN_JAON-15BYTH145_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15BYTH145
CATALOG_PART_NBR
HCS365/SM
HCS365-I/SM
HCS365T/SM
HCS365T-I/SM
HCS500/SM
HCS500-I/SM
HCS500T/SM
PIC12C508-04/SM
PIC12C508-04E/SM
PIC12C508-04I/SM
PIC12C508A-04/SM
PIC12C508A-04/SM048
PIC12C508A-04E/SM
PIC12C508A-04I/SM
PIC12C508AT-04/SM
PIC12C508AT-04/SM048
PIC12C508AT-04/SM096
PIC12C508AT-04/SM232
PIC12C508AT-04/SM233
PIC12C508AT-04E/SM
PIC12C508AT-04I/SM
PIC12C508AT-04I/SM112
PIC12C508AT-04I/SM142
PIC12C508AT-04I/SM194
PIC12C508AT-04I/SM218
PIC12C508AT-04I/SM224
PIC12C508AT-04I/SM226
PIC12C508AT-04I/SM236
PIC12C508T-04/SM
PIC12C508T-04/SM038
PIC12C508T-04I/SM
PIC12C509-04/SM
PIC12C509-04E/SM
PIC12C509-04I/SM
PIC12C509A-04/SM
PIC12C509A-04E/SM
PIC12C509A-04I/SM
PIC12C509AT-04/SM
PIC12C509AT-04/SM022
PIC12C509AT-04/SM091
PIC12C509AT-04E/SM
PIC12C509AT-04I/SM
PIC12C509AT-04I/SM135

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15BYTH145
CATALOG_PART_NBR
PIC12C509T-04/SM
PIC12C509T-04E/SM
PIC12C509T-04I/SM
PIC12C671-04/SM
PIC12C671-04/SMC01
PIC12C671-04E/SM
PIC12C671-04I/SM
PIC12C671-04I/SM050
PIC12C671-10/SM
PIC12C671-10I/SM
PIC12C671T-04/SM
PIC12C671T-04/SM067
PIC12C671T-04/SMC01
PIC12C671T-04E/SM
PIC12C671T-04I/SM
PIC12C671T-04I/SM040
PIC12C671T-04I/SM066
PIC12C671T-10I/SM
PIC12C671T-10I/SM070
PIC12C672-04/SM
PIC12C672-04E/SM
PIC12C672-04I/SM
PIC12C672-10/SM
PIC12C672-10E/SM
PIC12C672-10I/SM
PIC12C672T-04/SM
PIC12C672T-04I/SM
PIC12C672T-04I/SM028
PIC12CR509AT-04I/SM021
PIC12LC508A-04/SM
PIC12LC508A-04I/SM
PIC12LC508AT-04/SM
PIC12LC508AT-04I/SM172
PIC12LC509A-04/SM
PIC12LC509A-04I/SM
PIC12LC509AT-04I/SM
PIC12LC671-04/SM
PIC12LC671-04I/SM
PIC12LC672-04/SM
PIC12LC672-04I/SM